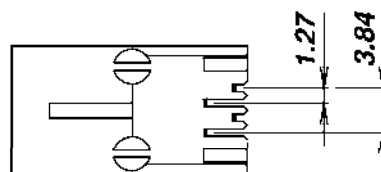


PCB LAYOUT
(Top View)



Note : Total Cd(cadmium) Content < 5PPM(mg/kg)
 Test Method : EN1122:2001 Method (ICP-AES)
 : Total Pb(Lead) Content < 100PPM(mg/kg)
 Test Method : US EPA3050B (ICP-AES)

SPECIFICATION :

1. Electrical Char.

Insulation Resistance : 500M-Ohm Min.
 Contact Resistance : 20milli-Ohm Max.
 Rating Current : 1.5A Max.
 Rating Voltage : 120V AC
 Dielectric Voltage : 1,000 RMS 60 Sec. Min.

2. Physical Char.

Housing : PBT Glass Filled (UL 94V-0)
 Color : Black Color
 Spring Wire : 0.35mm Thickness Phosphor Bronze
 Gold Plating Over Nickel
 Temperature Range : - 25 +90 C
 Durability : 500 Mating cycles Min.

HC-006-4-A-LX-N ← FLANGELESS

A=4p4c

L=Lead Free

Gold plated
 1=15u, 3=50u
 2=30u, 4= 6 u

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TITLE

RJ11 SIDE ENTRY PCB JACK
 UL & cUL FILE NO. E131820

MODULAR JACKS ASSY FOR
HC-006-4-A-LX-N

SCALE SIZE DWG. NO.9601 SERIES

DWG. NO.

AS006002-L

| NOT SCALED DRAWING | TOLERANCE UNLESS OTHERWISE NOTICE | INCH | MM | DR. | DATE |
|------------------------|-----------------------------------|-----------|----------------|--------|------------|
| THIRD ANGLE PROJECTION | LINEAR | 00±0.01 | 00±0.25 | Steven | JAN-12 '05 |
| | | 000±0.005 | 000±0.13 | Johnn | JAN-12 '05 |
| | ANGLE ±0°30' | RADIL | +0.45 -0.15 | Billy | JAN-12 '05 |